

**Process For Manufacturing A Piezoelectric Structure For A Radiofrequency Device,
Which Structure Can Be Used To Transfer A Piezoelectric Layer, And Process For
Transferring Such A Piezoelectric Layer**

Abstract

- 5 A process for manufacturing a piezoelectric structure (10) for a radiofrequency device, said process being characterized in that it comprises providing a substrate of piezoelectric material (20), providing a carrier substrate (100), providing a dielectric bonding layer (1001) on the substrate of piezoelectric material (20), a step (1') of joining the substrate of piezoelectric material (20) to the carrier substrate (100) via the dielectric bonding layer (1001), and a
- 10 thinning step (2') for forming the piezoelectric structure (10), which consists of a layer of piezoelectric material (200) joined to a carrier substrate (100) via the dielectric bonding layer (1001).

Fig. 1